N Channel Enhancement

- High speed switching
- Very low switching losses
- Fully controllable dv/dt
- High blocking voltage with low on-resistance
- Fast intrinsic diode with low reverse recovery (Qrr)
- Temperature independent turn-off switching losses
- Halogen free, RoHS compliant

- Cooling effort reduction
- Efficiency improvement
- Reduced cooling requirements
- Increased power density
- Increased system switching frequency



- On-board charger/PFC
- EV battery chargers
- Booster/DC-DC converter
- Switch mode power supplies

(T_C = 25 ,

$R_{th\ (j-c),max}$)

(Tc = 25°C unless otherwise specified)

$V_{DS,max}$	Drain source voltage	1200	V	V_{GS} = 0V, I_D = 100μA	
$V_{GS,max}$	Gate source voltage	-8 /+22	V	Absolute maximum values	Note1
$V_{GSpulse}$	Gate-source voltage,max. transient voltage	-10 /+25	V	$t_p \leq 0.5\mu s$, D 0.01	
V_{GSop}	Gate source voltage	-4 /+18	V		

Q_{gs}	Gate source charge	-	16	-	nC	V_{DS} = 800V, V -4/+18V = 26A	Fig 12
Q_{gd}	Gate drain charge	-	17	-			
Q_g	Gate charge	-	51	-			

(Tc = 25°C unless otc

[redacted]

[redacted]

[redacted]

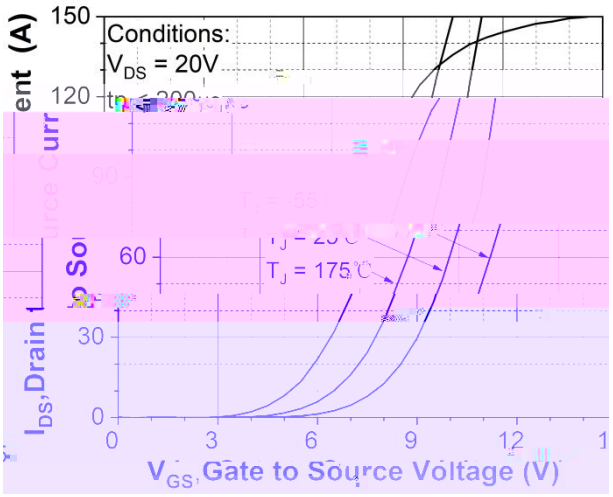


Figure 7. Transfer characteristic for various junction temperatures

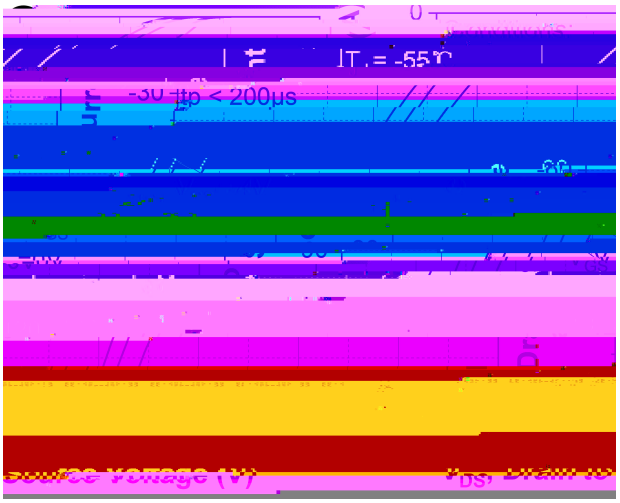


Figure 8. Body diode characteristic at T_J = -55 ºC

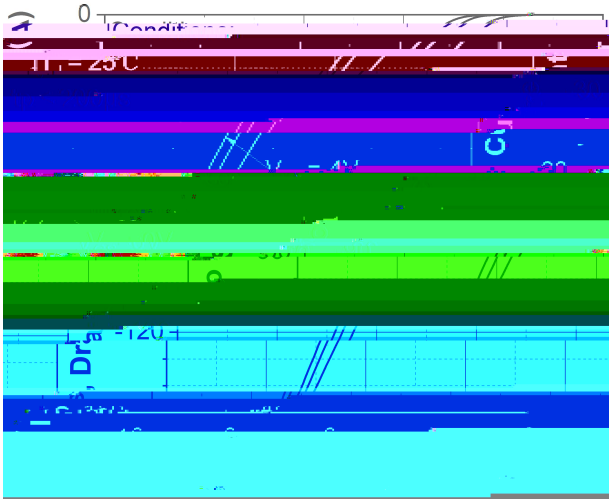


Figure 9. Body diode characteristic at T_J = 25 ºC

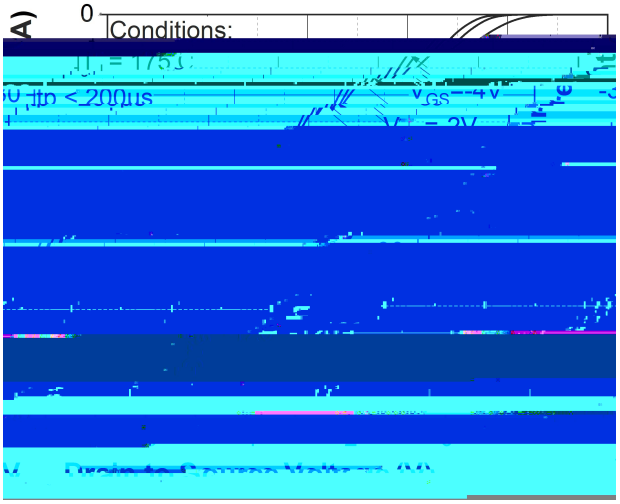


Figure 10. Body diode characteristic at T_J = 175ºC

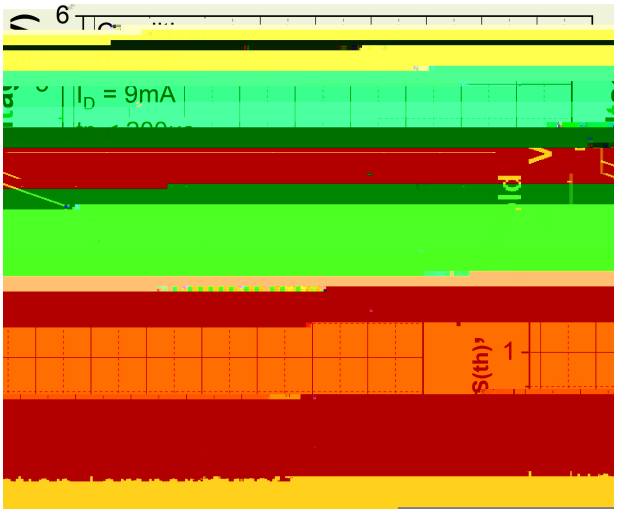


Figure 11. Threshold voltage vs. temperature

Figure 12. Gate charge characteristic

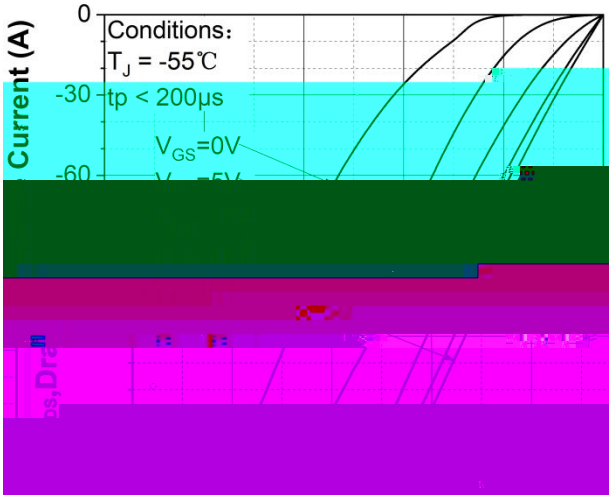


Figure 13. 3rd quadrant characteristic at T_J = -55 ºC

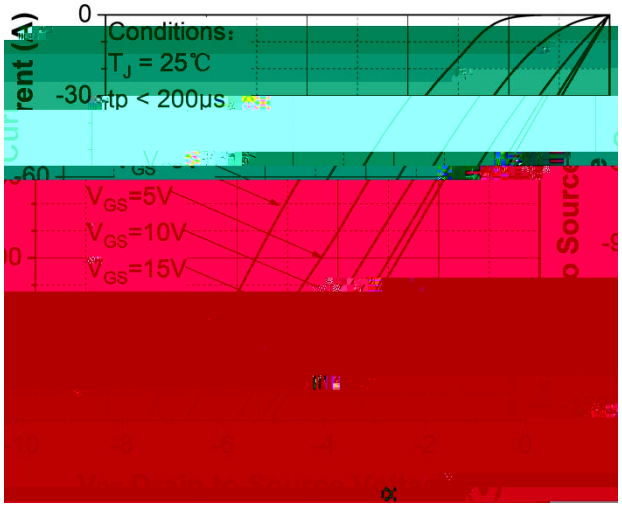


Figure 14. 3rd quadrant characteristic at T_J = 25 ºC

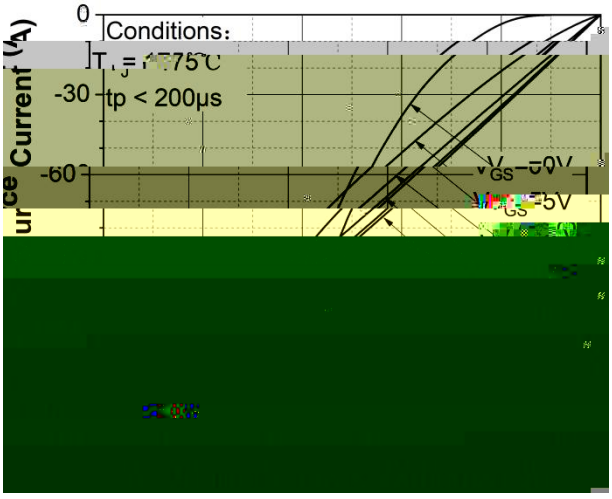


Figure 15. 3rd quadrant characteristic at T_J = 175 ºC

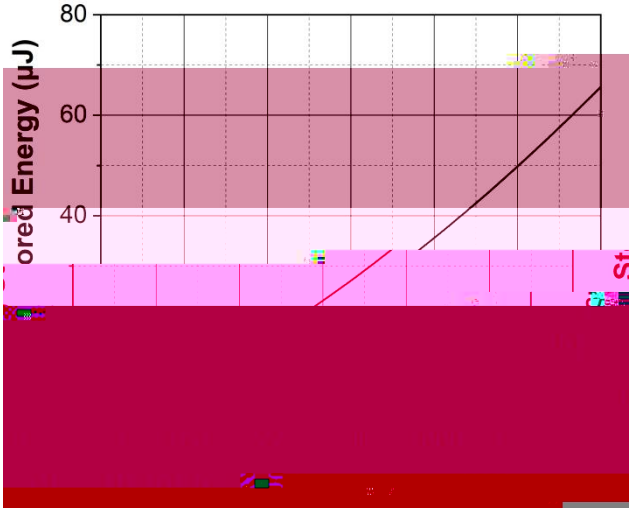


Figure 16. Output capacitor stored energy



Figure 17. Capacitances vs. drain-source voltage (0 - 200V)

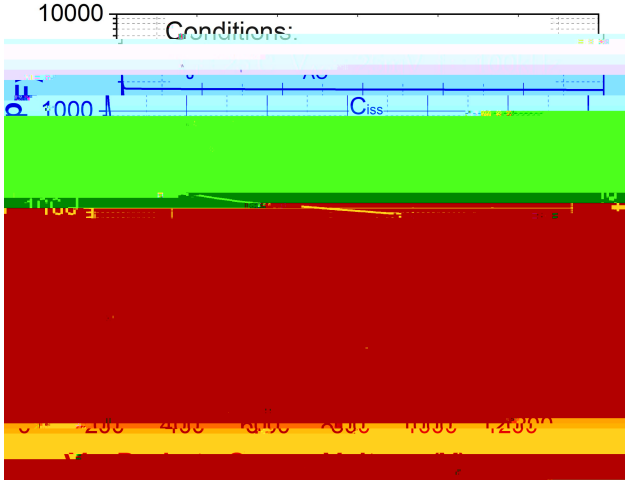


Figure 18. Capacitances vs. drain-source voltage (0 - 1200V)

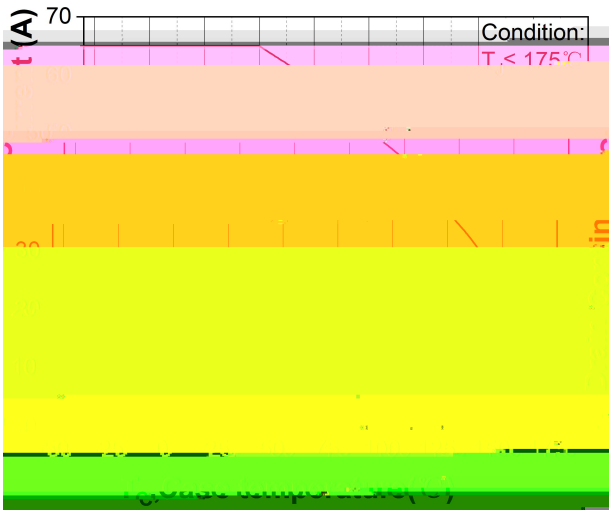


Figure 19. Continuous drain current derating vs. case temperature



Figure 20. Maximum power dissipation derating vs. case temperature

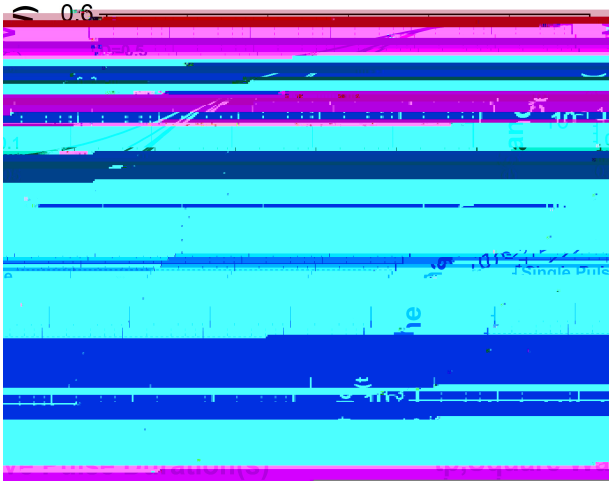


Figure 21. Transient thermal impedance (junction - case)

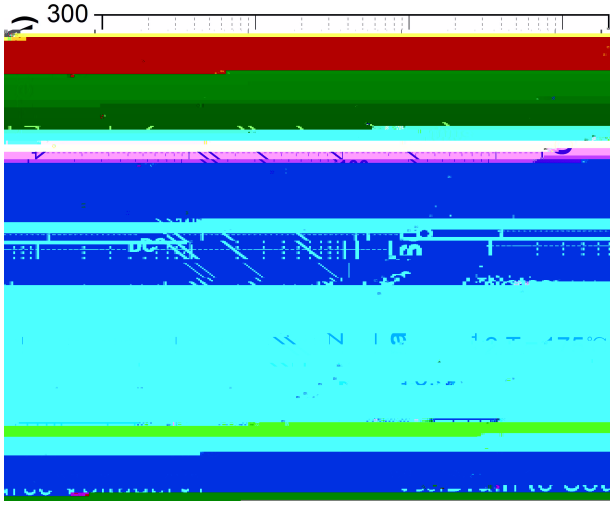


Figure 22. Safe operating area

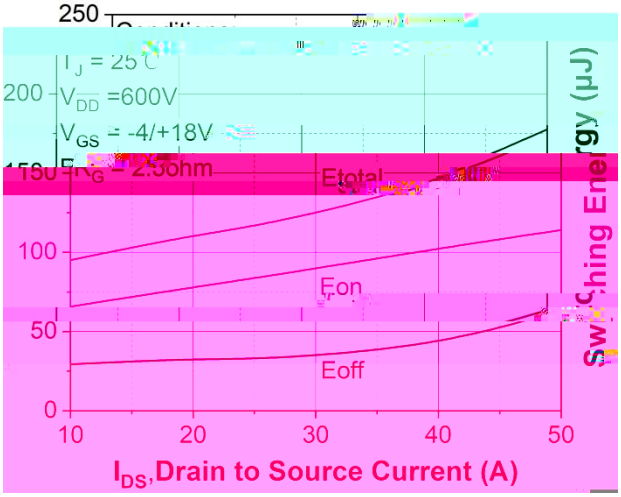


Figure 23. Clamped Inductive switching energy vs. drain current (V_{DD} = 600V)

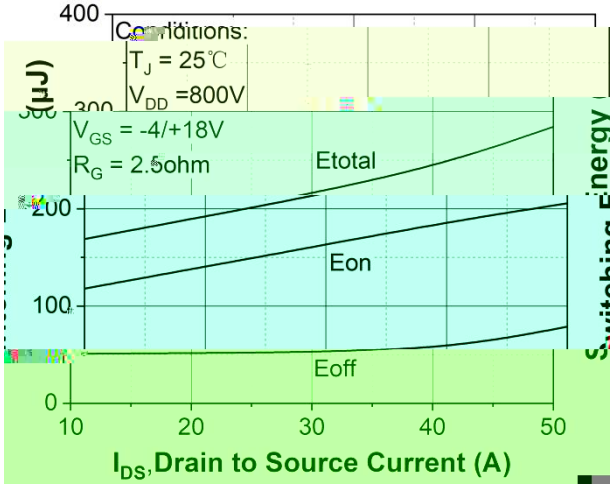


Figure 24. Clamped inductive switching energy vs. drain current (V_{DD} = 800V)

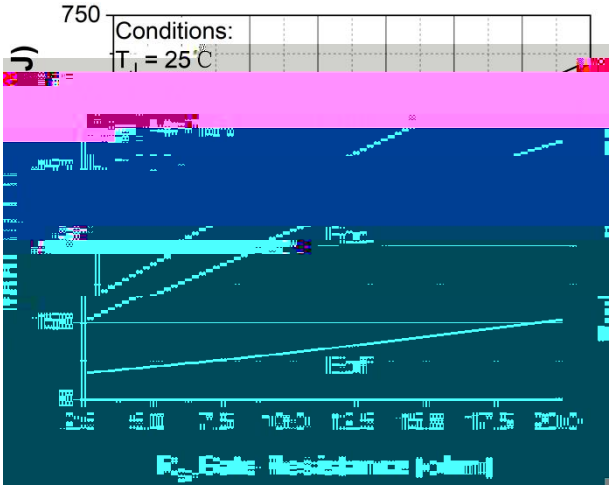


Figure 25. Clamped inductive switching energy vs. R_G (ext)

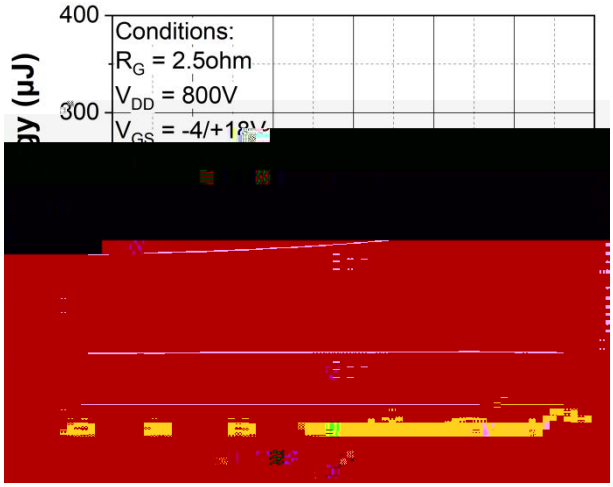


Figure 26. Clamped inductive switching energy vs. temperature

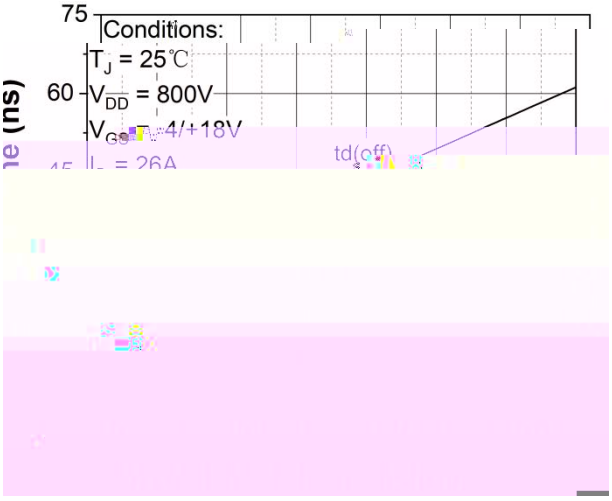
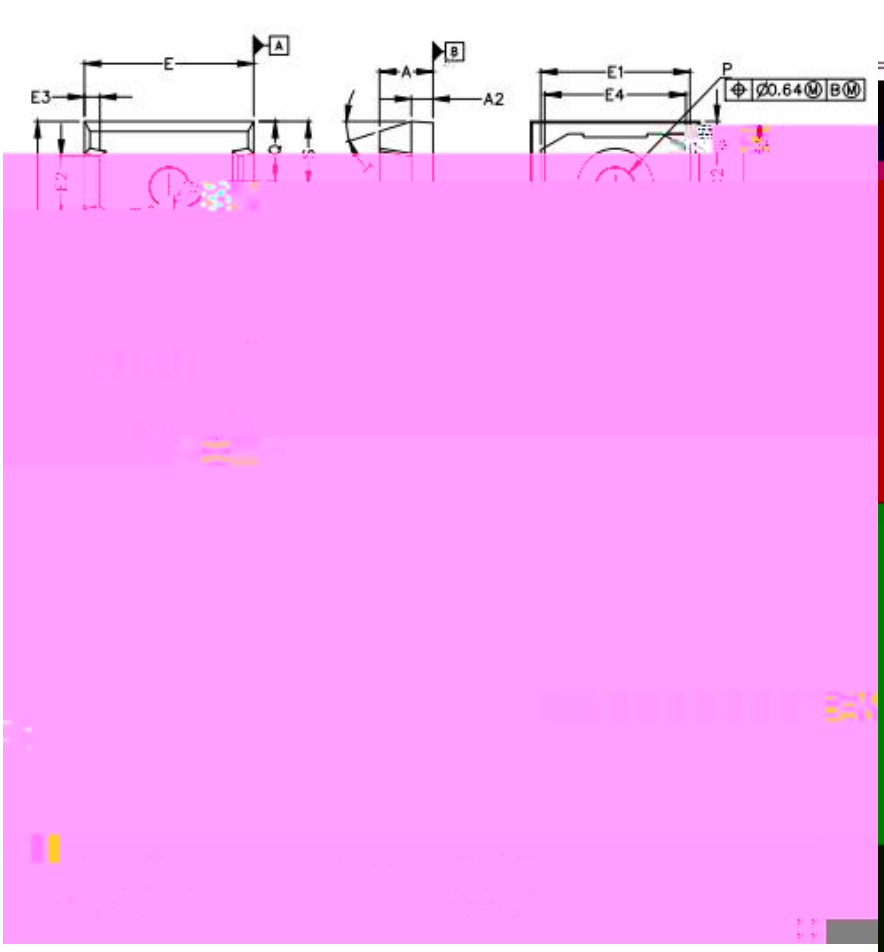
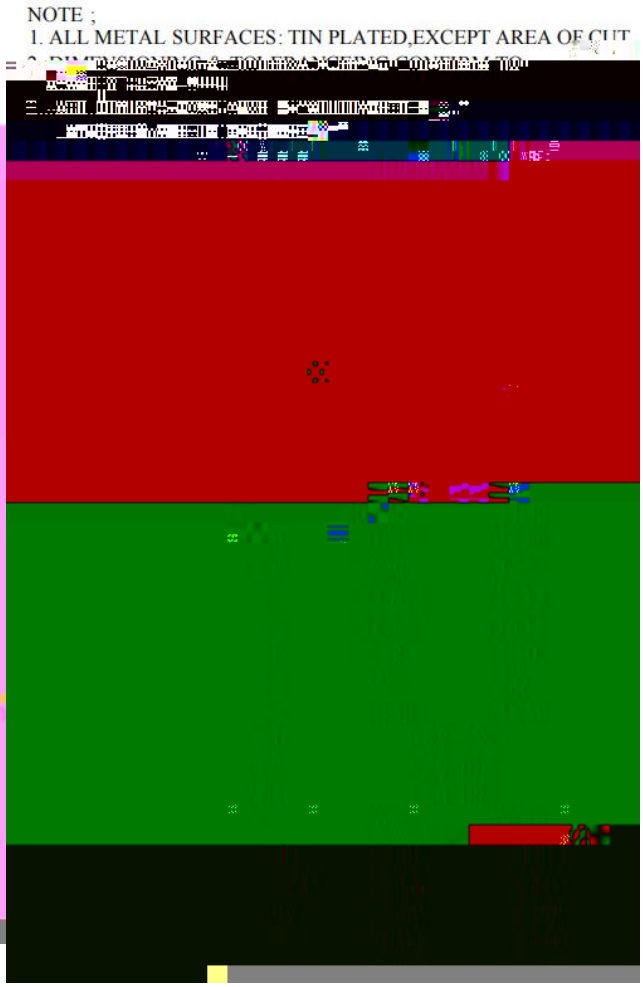


Figure 27. Switching times vs. R_G (ext)

(TO-247-4L-C)


E
E3
A
B
A
A2
E1
E4
P
Ø0.64Ⓜ BⓂ


NOTE ;
1. ALL METAL SURFACES: TIN PLATED,EXCEPT AREA OF CUT

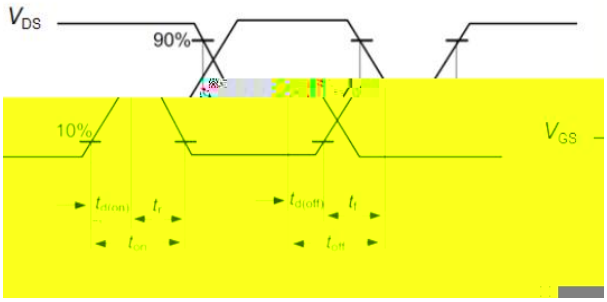


Figure A. Definition of switching times

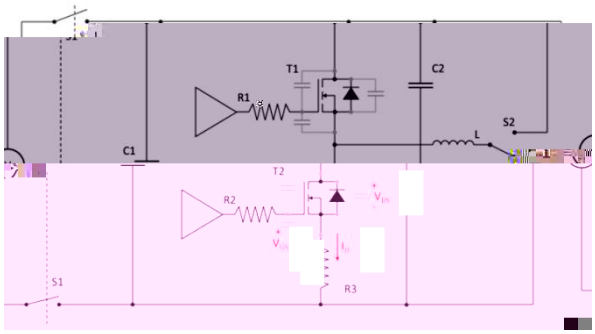


Figure B. Dynamic test circuit

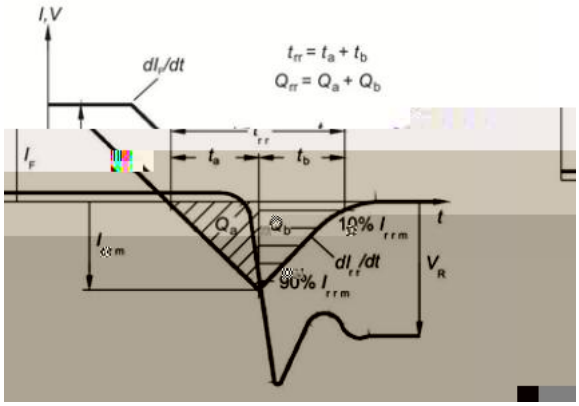


Figure C. Definition of body diode switching characteristics

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1.
The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/ EC (RoHS2), as implemented January 2, 2013.

2.
REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Sichain representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

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7. Except as otherwise explicitly approved by Sichain in a written document signed by authorized representatives of Sichain, Sichain' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.

8. For use of our products in applications requiring a high degree of reliability (as exemplified below), please contact and consult with a Sichain representatives, for example but not limited to: transportation equipment,primary communication equipment,traffic lights,fire/crime prevention, safety equipment, medical systems, and power transmission systems.